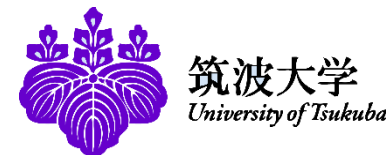


Total Ionization Damage Compensations in Double Silicon-on-Insulator(SOI) Pixel Sensors

HONDA Shunsuke
University of Tsukuba, JAPAN



Co Authors:

K. Hara, M. Asano, T. Maeda, N. Tobita^(Univ. Tsukuba),
Y. Arai, T. Miyoshi^(KEK), M. Ohno^(AIST), T. Hatsui^(RIKEN), T. Tsuru^(Kyoto Univ.),
N. Miura, H. Kasai^(Lapis Miyagi), M. Okihara^(Lapis)

✓ related presentations:

[T. Miyoshi et al.](#) : Monolithic pixel detectors fabricated with single and double SOI wafers

[A. Takeda et al.](#) : Development and Evaluation of Event-Driven SOI Pixel Detector for X-ray Astronomy

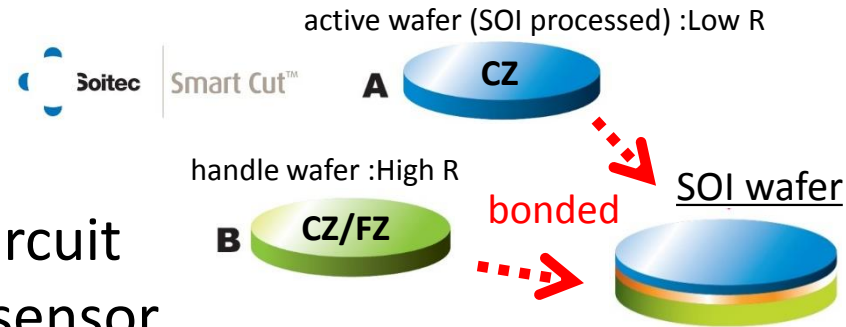
[H. Matsumura et al.](#) : Development of X-ray SOI Pixel Sensors: Investigation of Charge-Collection Efficiency

[K. Kasahara et al.](#) : Development of Superconducting Tunnel Junction Photon Detector on SOI Preamplifier Board to Search for Radiative decays of Cosmic Background Neutrino

SOI Pixel Sensors

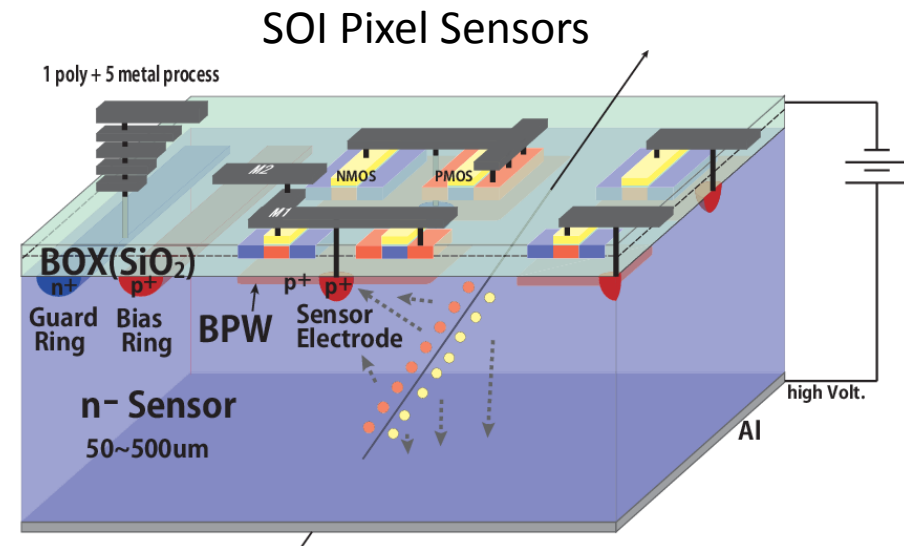
Technology characteristics:

- ✓ Bonded SOI wafers by SOITEC Co. with low resistive “active wafer” for circuit and high resistive “handle wafer” for sensor.
- ✓ Commercial Fully-Depleted(FD) SOI process ($0.20\mu\text{m}$) by Lapis Semiconductor Ltd.



Pros:

- **bonded wafer**
thick X-ray, thin HEP :fully depleted
- **FD-SOI features**
low-power, hi-speed, no latch-up,
$1\text{K}-300\text{C}$ operational
- **monolithic (no metal-bonding)**
fab. cost, small material, high density pixels



SOI Pixel Sensors

Cons:

- **cross-talk between the sensor and the circuit**

because of very thin BOX layer: 200nm

- **back-gate effect**

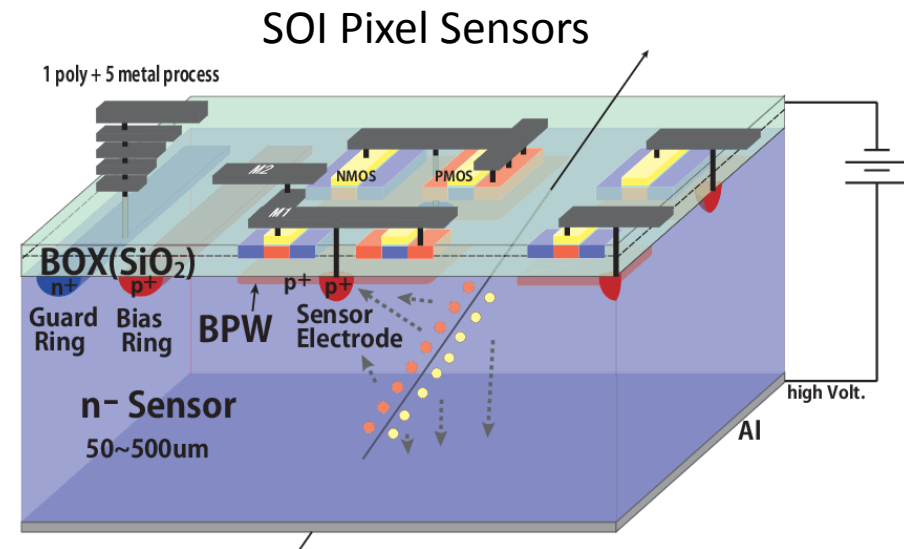
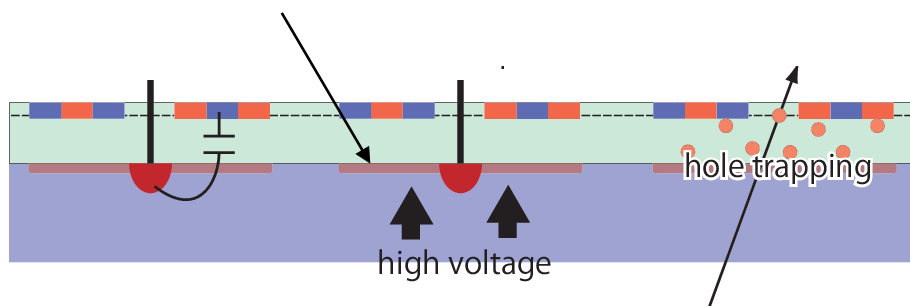
readout affected by bias voltage to the back

- **radiation effect - TID effect**

readout affected by holes trapped in BOX layer

BPW(Buried P-Well) is effective to reduce the back-gate effect

- increase capacitance.....

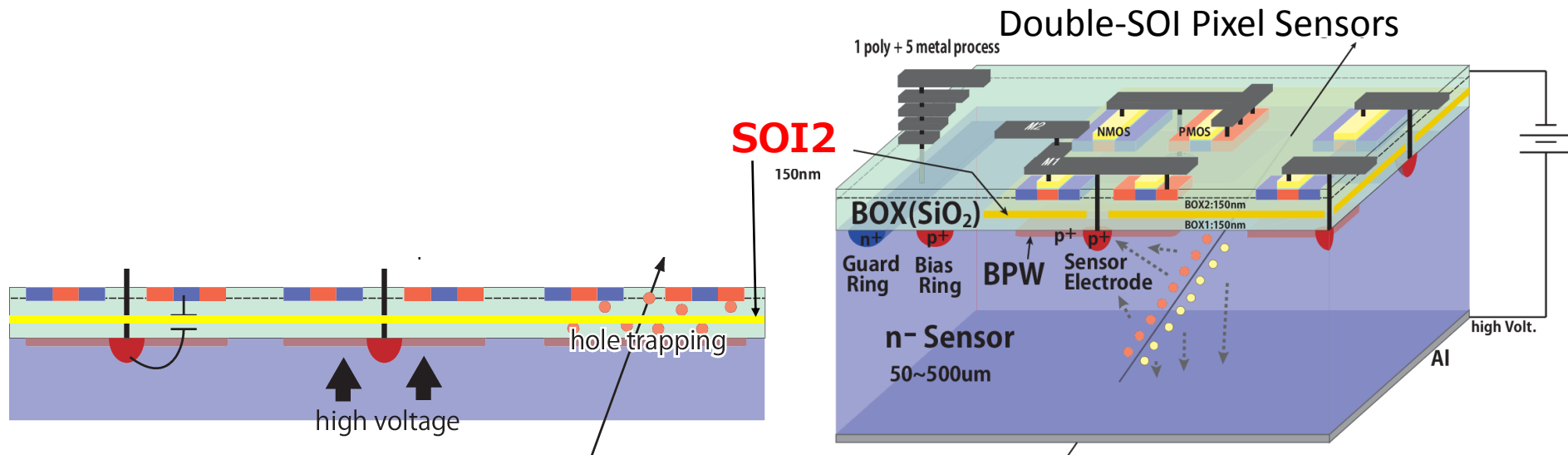


SOI Pixel Sensors

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- **back-gate effect**
readout affected by bias voltage to the back
- **radiation effect - TID effect**
readout affected by holes trapped in BOX layer

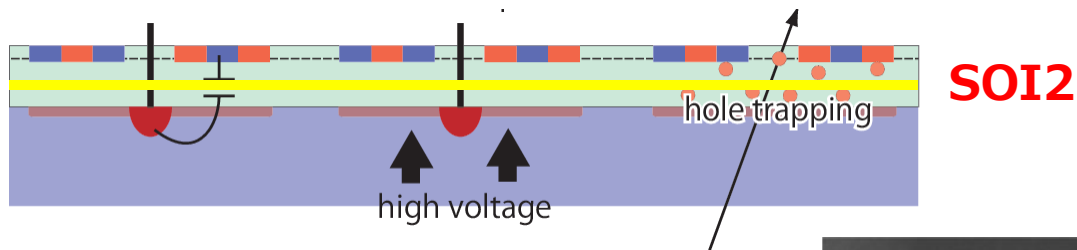
To solve these cons, **Innovative Double-SOI (SOI2 layer) is introduced!!**



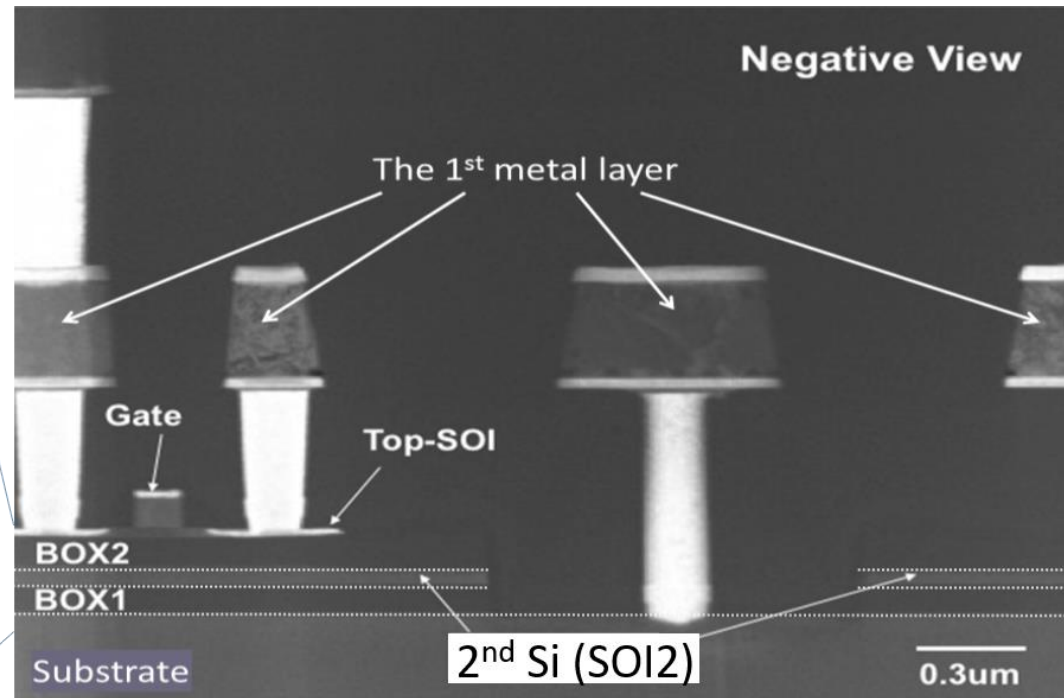
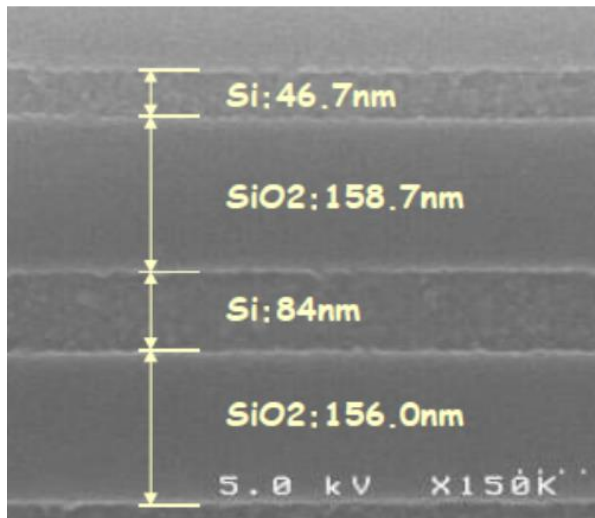
Double-SOI process

2nd Si layer (SOI2) made by SOI-process twice

- ✓ shield against cross-talk & back-gate effect : **NOW IN PROGRESS**
- ✓ V control to compensate trapped hole charge : **TODAY'S TALK**



$\rho_{SOI2} \sim 10 \Omega \text{cm}$ with CoSi₂: $\sim 170 \text{k}\Omega/\text{sq}$
w/o CoSi₂: $\sim 1 \text{M}\Omega/\text{sq}$

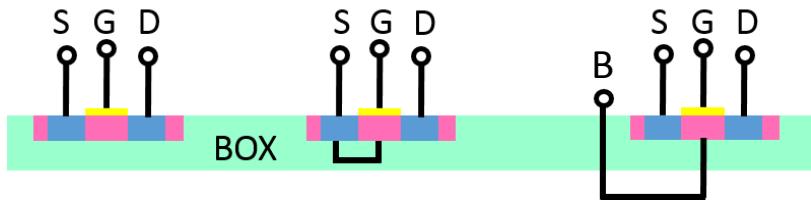


Transistor Test Elements Groups (TrTEG)

TrTEG6 : 3kGy – 2MGy (200Mrad)

18 species each for NMOS/PMOS

- several L, W ($W_{eff}=W \times m$).
- low, normal, high threshold volt.
- 3 kinds of body connections.



body floating
(bf)

source-tie
- type1(s-tie)
- type2(s-tie2)

multi-body-tie
can be applied a variable volt.
(multib-tie)

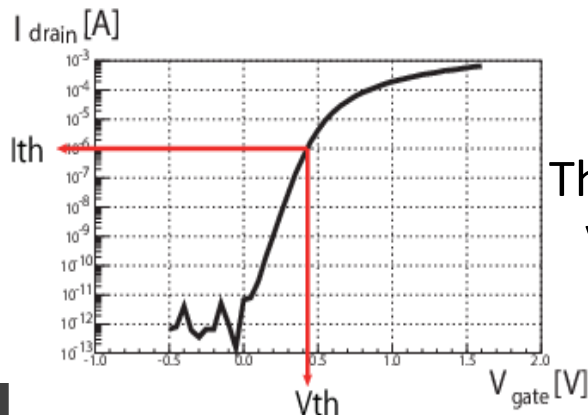
Total dose in high energy physics experiments

LHC(HL-LHC) ATLAS - Inner Pixel Detector
:158 kGy/yr (1.6 MGy/yr)

ILC ILD - Vertex Detector
:1 kGy/yr

L[um]	W[um]	m	Comment
0.20	5	4	nvt_bf
0.50	5	10	nvt_bf
1.00	5	20	nvt_bf
0.20	5	4	lvt_bf
0.50	5	10	lvt_bf
1.00	5	20	lvt_bf
0.35	5	7	iohvt_bf
0.35	5	7	iohvt_bf
0.20	5	4	lvt_s-tie
0.50	5	10	lvt_s-tie
1.00	5	20	lvt_s-tie
0.40	10	4	nvt_s-tie2
0.60	6	10	nvt_s-tie2
1.00	5	20	nvt_s-tie2
0.20	5	4	nvt_multib-tie
0.50	5	10	nvt_multib-tie
1.00	5	20	nvt_multib-tie
1.00	5	20	ios-tie

Measure I_d - V_g curve before/after irradiations.



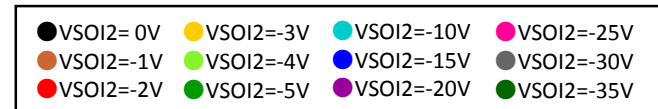
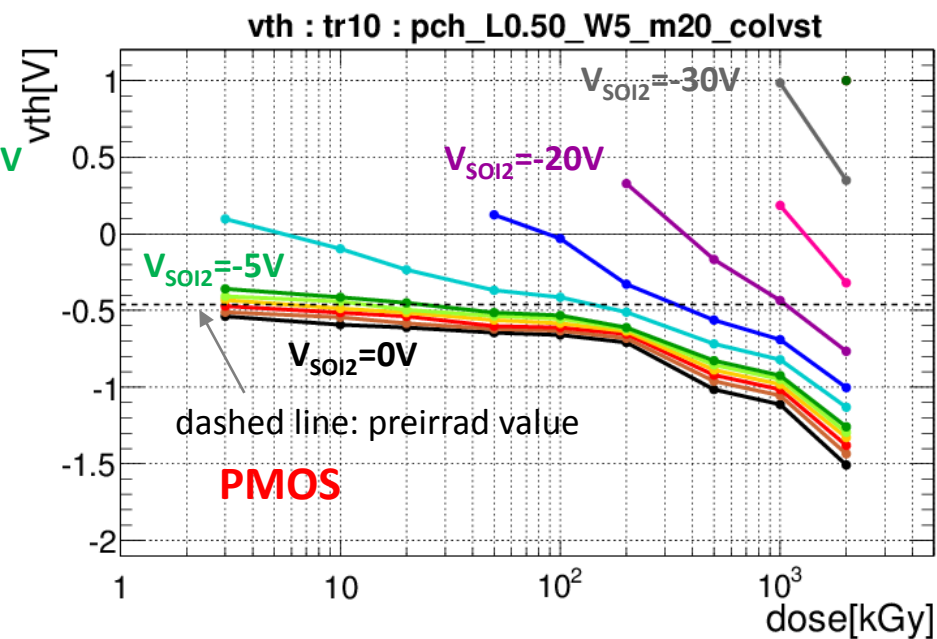
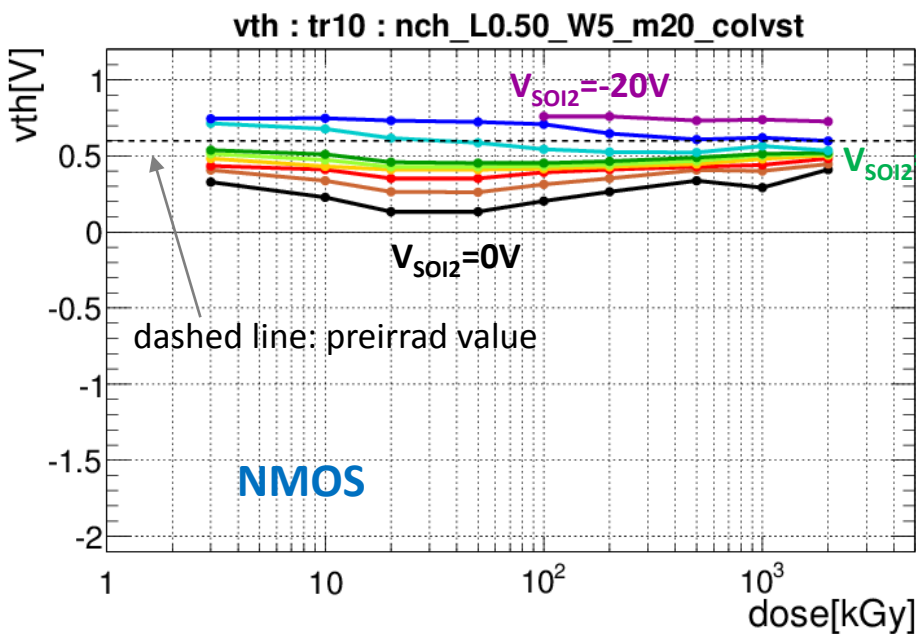
Threshold (V_{th}):
 $V_g @ I_d = (100nA) \times (W_{eff}/L)$

Vth Shifts – typical TR

tr10 : L0.5_W5_m20_colvst

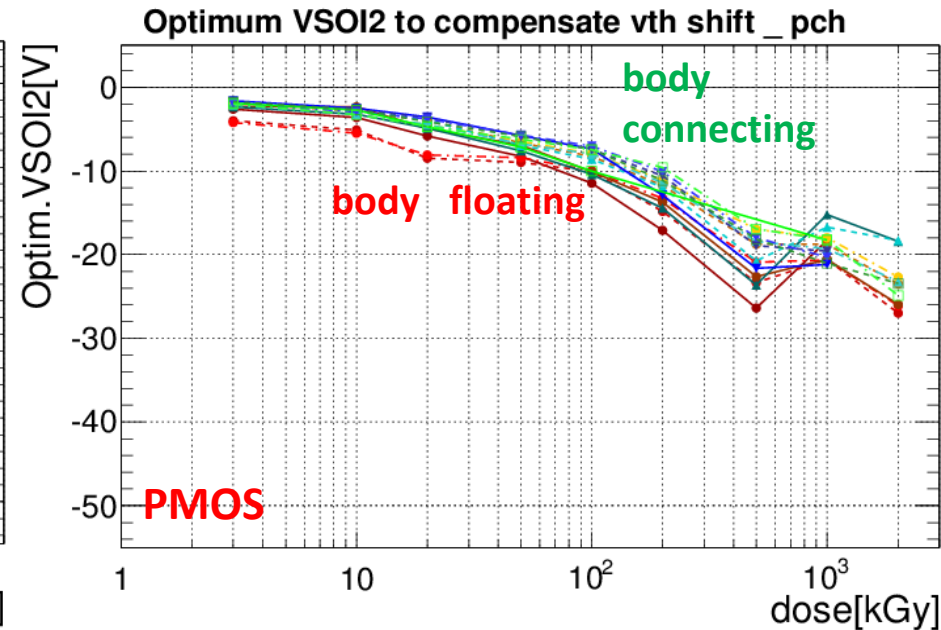
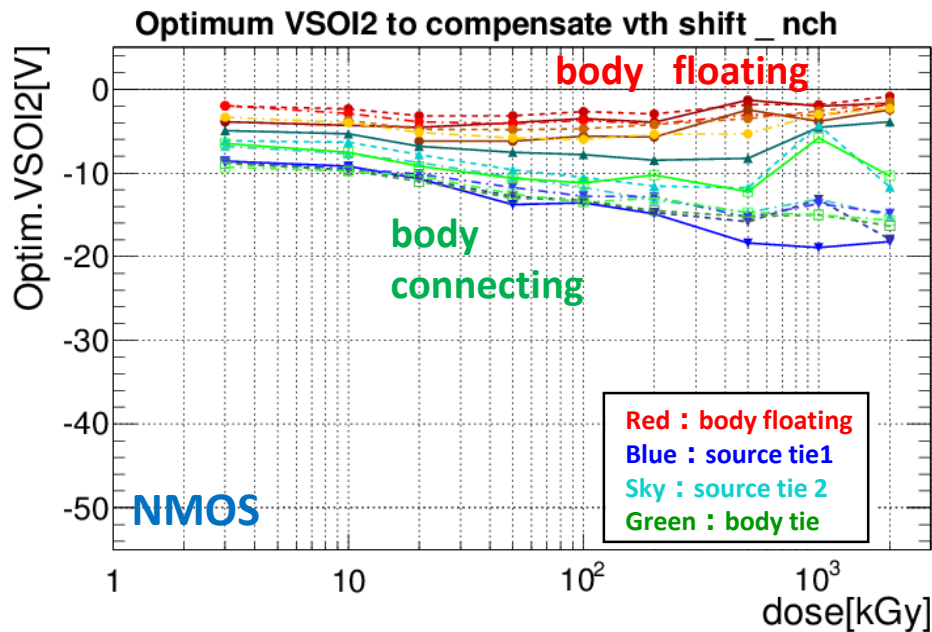
Thresholds shift negatively due to holes by irradiation.

**By applying V_{SOI2} properly,
the threshold can be recovered to the pre-irrad value.**



Vth Shifts – all TR types

Optimum V_{SOI2} : V_{SOI2} per dose to recover the transistor thresholds to the pre-irrad values measured at $V_{SOI2}=0$

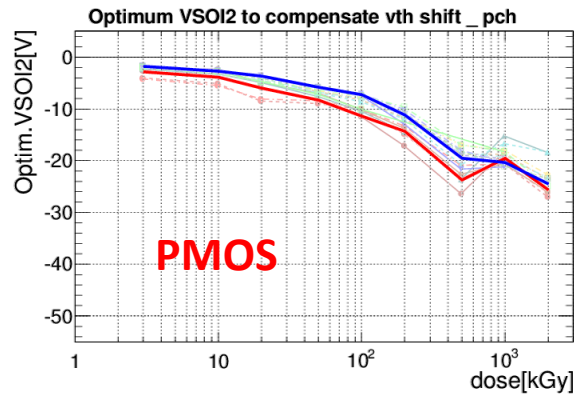
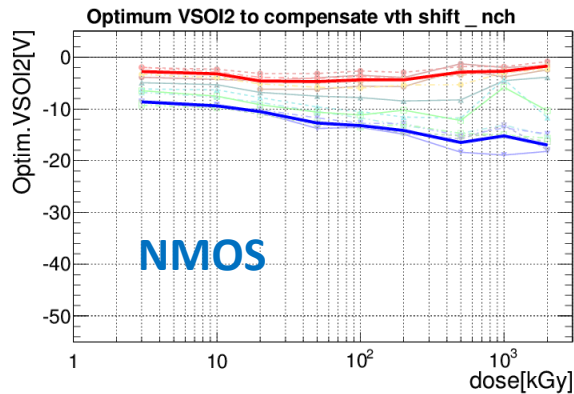


Noticeable differences are observed between NMOS & PMOS TRs, among body connections notably in NMOS.

Separate V_{SOI2} settings may be optimum to compensate TID.

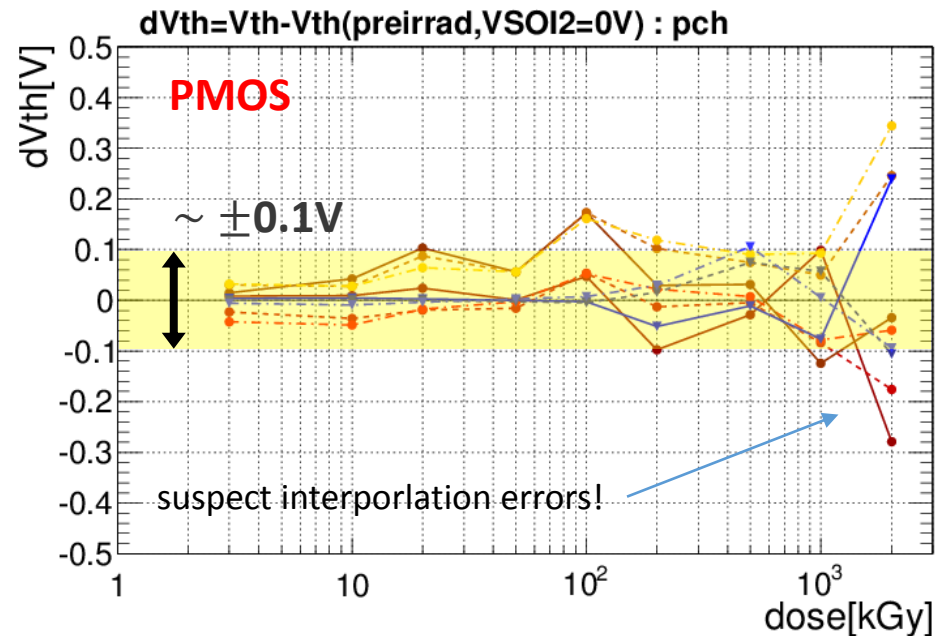
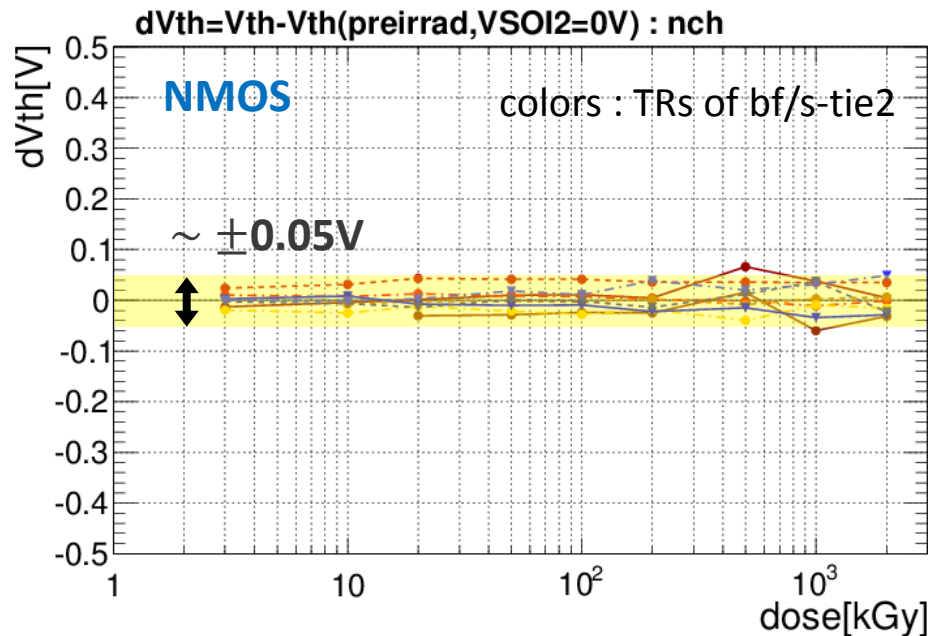
-example case: 4-voltages for NMOS/PMOS, bf/s-tie2. (s-tie1,b-tie are not considered)

Vth Compensation-example case



Red : average of body floating TRs
Blue : average of source tie2 TRs

Applying the 4 average curves for each V_{SOI2} type,
transistors are recovered in the range of $\pm 0.05V$ for NMOS, $\pm 0.1V$ for PMOS



Pixel Sensor (INTPIX)

INTPIXh2:10kGy-100kGy (10Mrad)

Integrated-type pixel sensor

-Pixel Size: 18 μ m x 18 μ m

-Handle: Cz(n,0.7k Ω cm)

-SOI2(common to all TRs): Cz(p,10 Ω cm)

-BPW(for shield back-bias effects) : GNDed

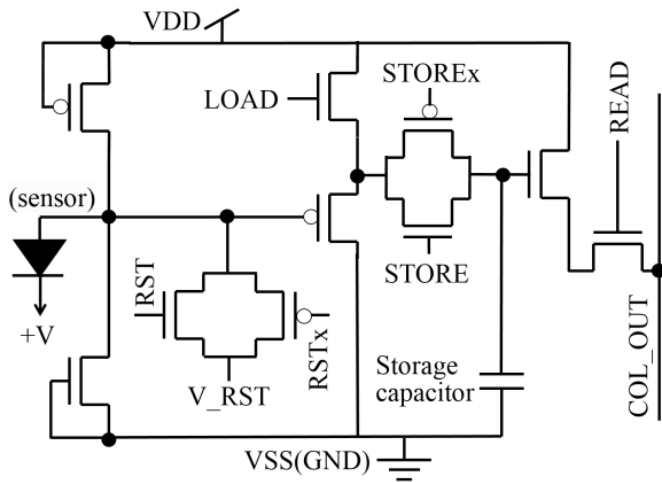
Total dose in high energy physics experiments

LHC(HL-LHC) ATLAS - Inner Pixel Detector

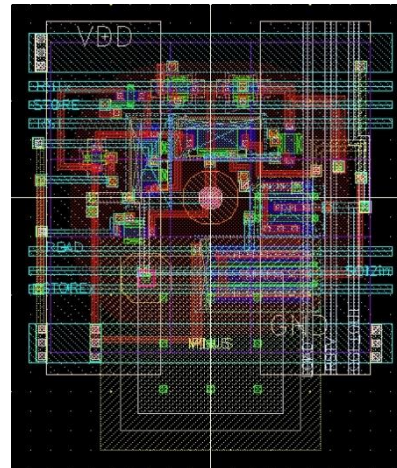
:158 kGy/yr (1.6 MGy/yr)

ILC ILD - Vertex Detector

:1 kGy/yr



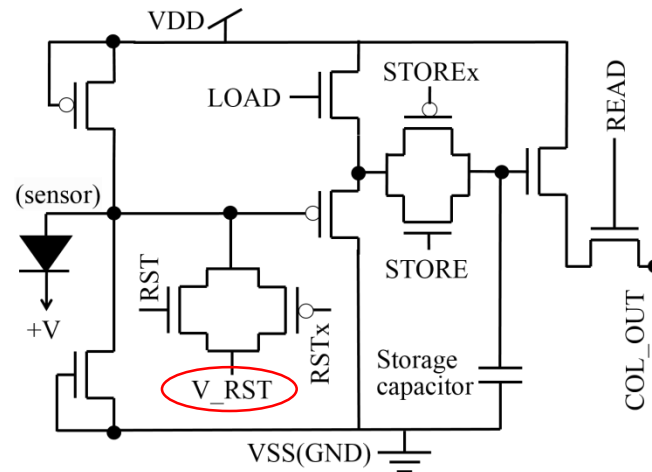
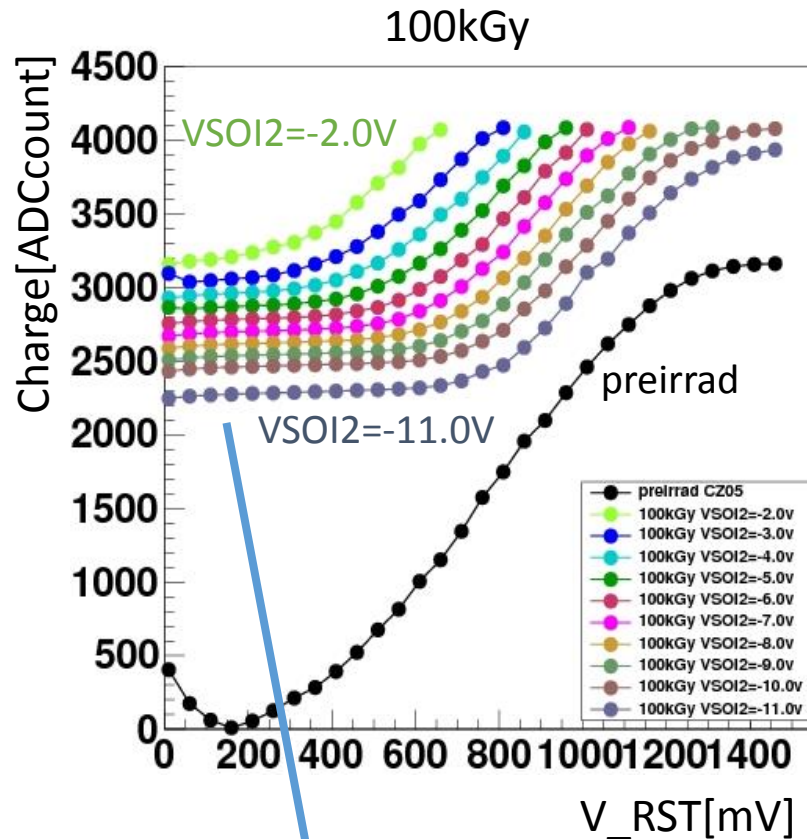
on-pixel circuit



Evaluate the functionality of electronics & response to IR-laser.

Reset Voltage Response

The functionality of electronics by “injecting” RESET voltage (V_{RST}).



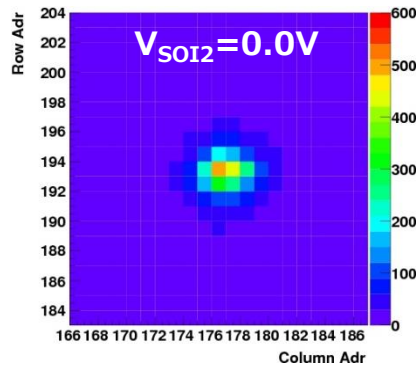
The sensor irradiated to 100kGy is recovered its functionality by V_{SOI2} .

But continuous calibrations per dose are required...

Dynamic range is not fully recovered : single V_{SOI2} is employed.

V_{SOI2} depending on transistor type is preferred.

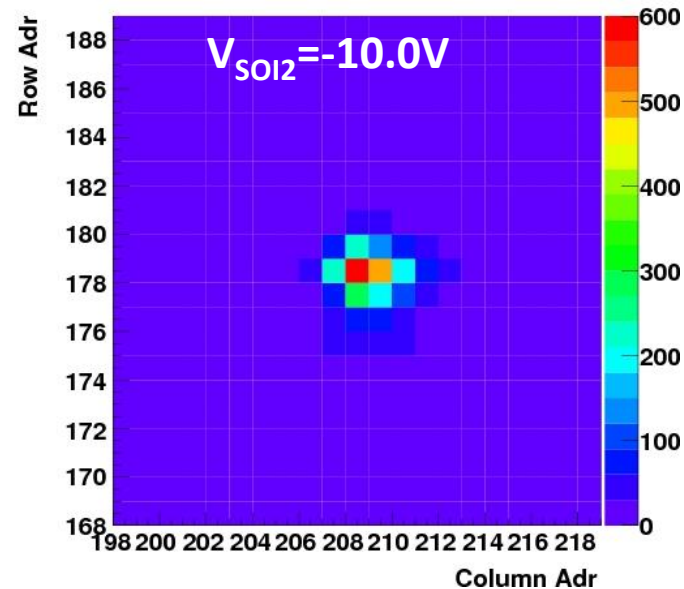
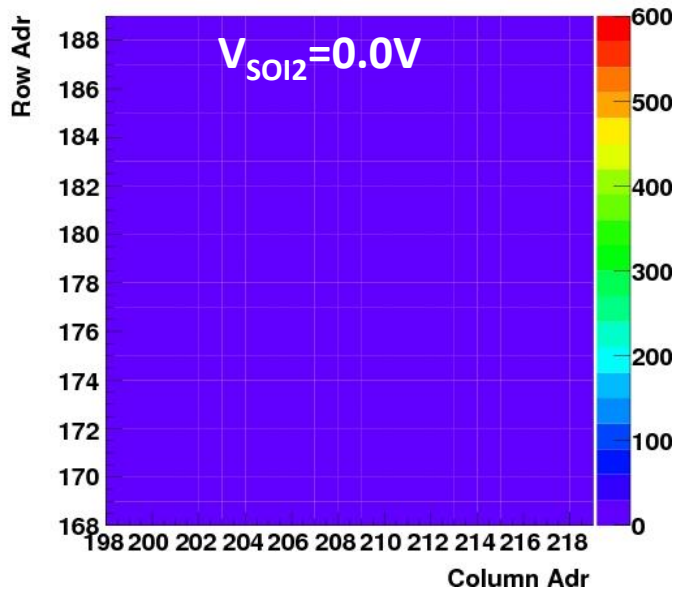
pre-irrad sample



Light Image = ADC(light) – ADC(pedestal)

- Int. time : 120ns
- back bias voltage : 100V
- reset voltage : 0.85V

100kGy sample



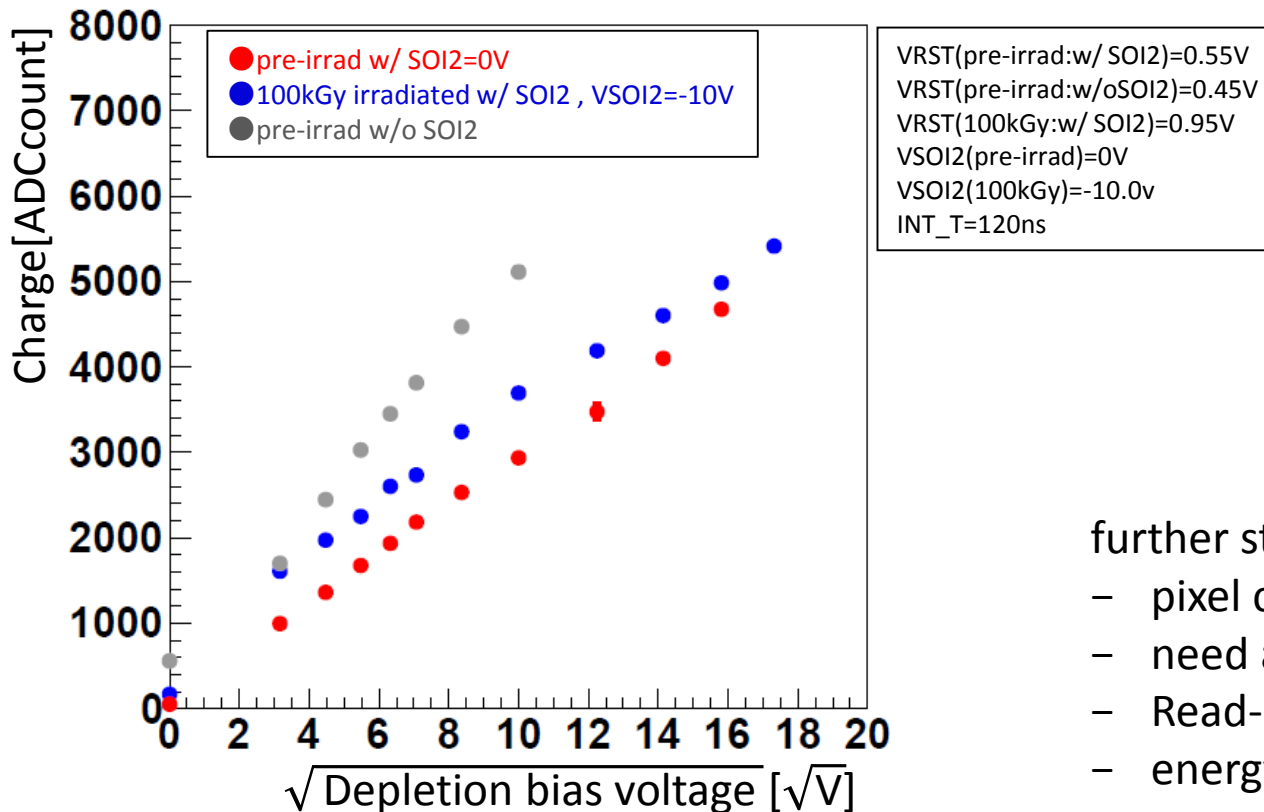
The response is almost saturated...

The image is obtained !

IR-Laser Response: ADC curve

Even after irradiated up to 100kGy,
obtained the same linearity and sensitivity as pre-irrad one.

Single-wafer sensor(w/o SOI2) has a higher gain than double-SOI-wafer one.
(due to smaller SOI2-sensor capacitance)



further studies are now in progress on

- pixel cross talk
- need a higher gain ?
- Read-out buffer response w/ SOI2
- energy peak of γ -ray sources

Summary

We are developing SOI pixel sensors for high energy physics.

Double-SOI can compensate the TID.

- Threshold voltage of transistors is recoverable.
- Sensor response is also recoverable.

(Data with higher doses will come soon!)

- The optimum V_{SOI2} are different among NMOS/PMOS, body-connections
- Design based on the obtained information is next step to further minimize TID effects.
- Other SOI2 properties are being evaluated.

By employing innovative double SOI technology, the radiation tolerance (TID) has been enhanced substantially.

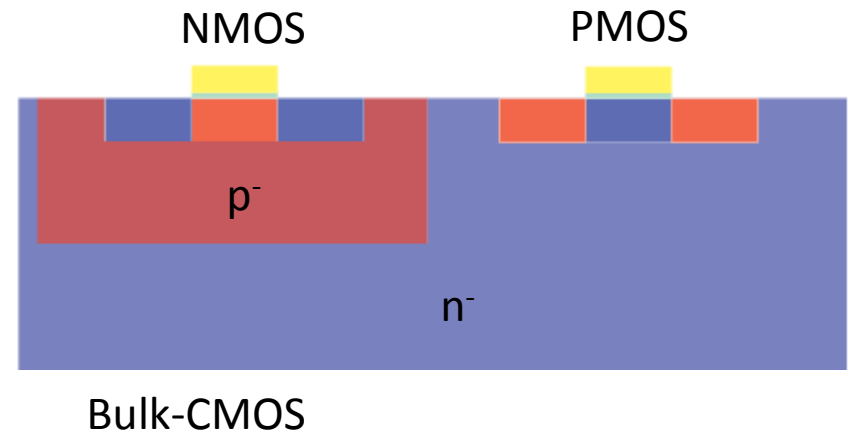
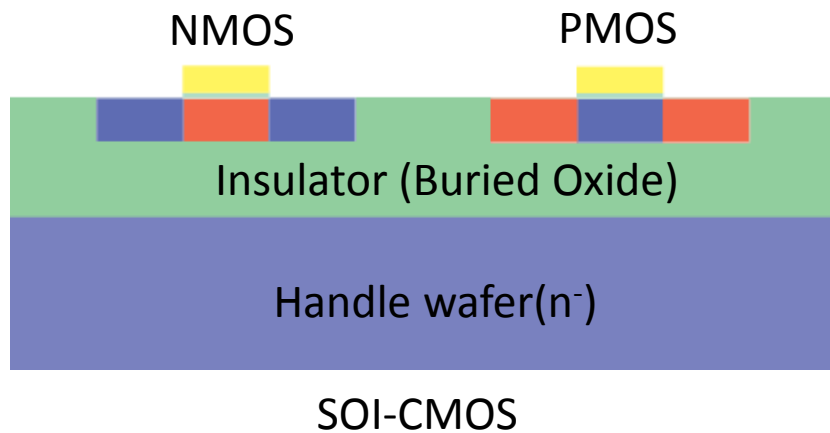
Designing pixel sensors for future collider experiments is set forward

BACK UP >>>

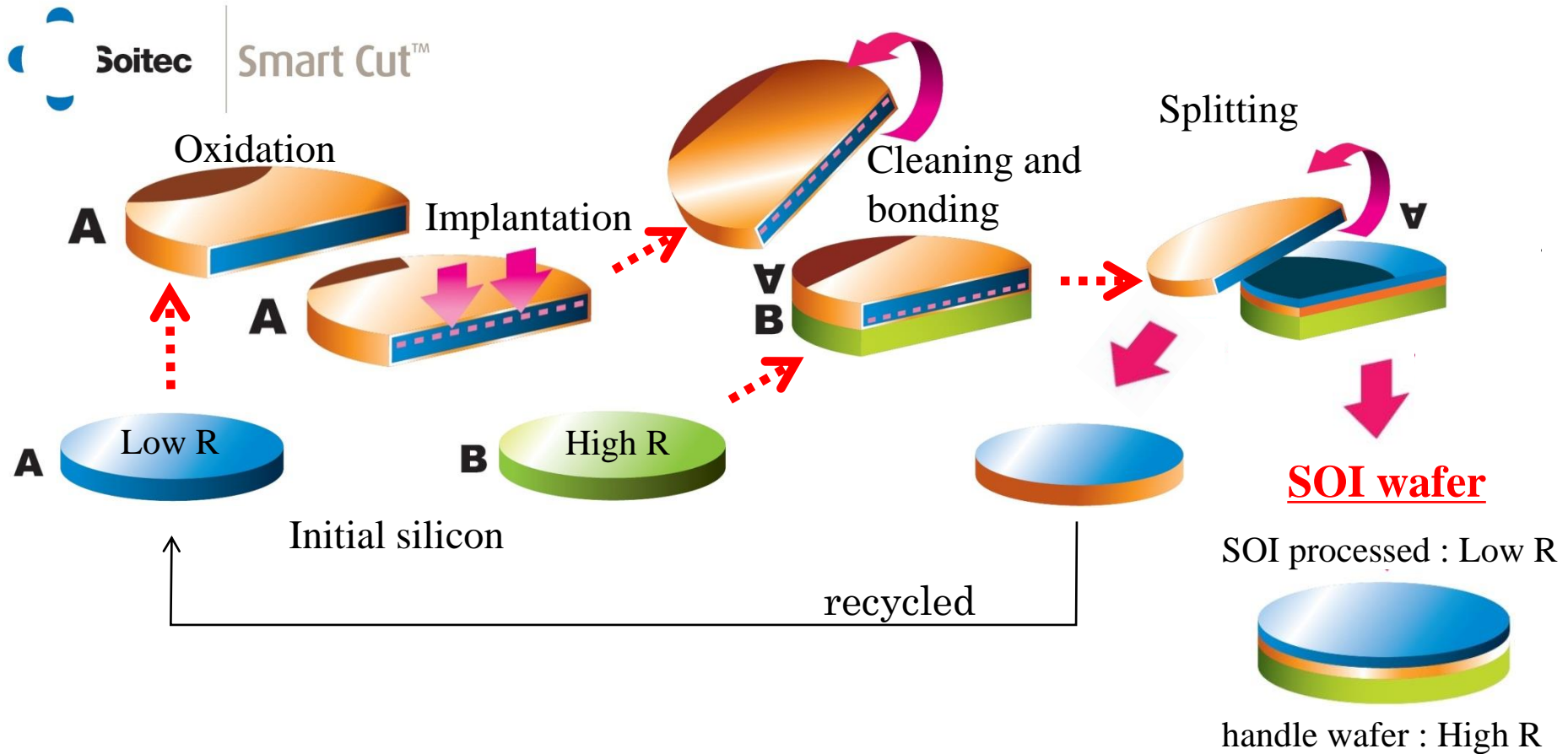
Fully-Depleted Silicon-on-Insulator(SOI) Technology

SOI – Transistors are isolated by the insulator.

FD – No parasitic capacitance.



SOI Wafer Production

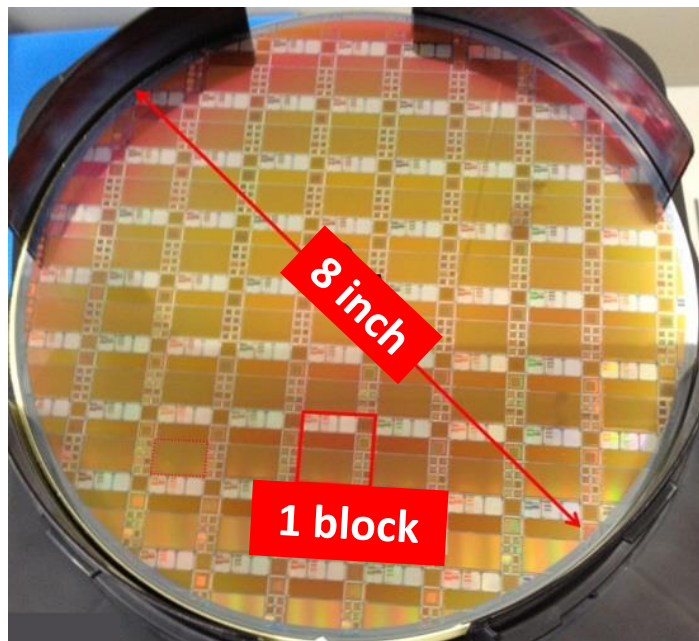


Main process parameters (Lapis Semiconductor Co. Ltd.):

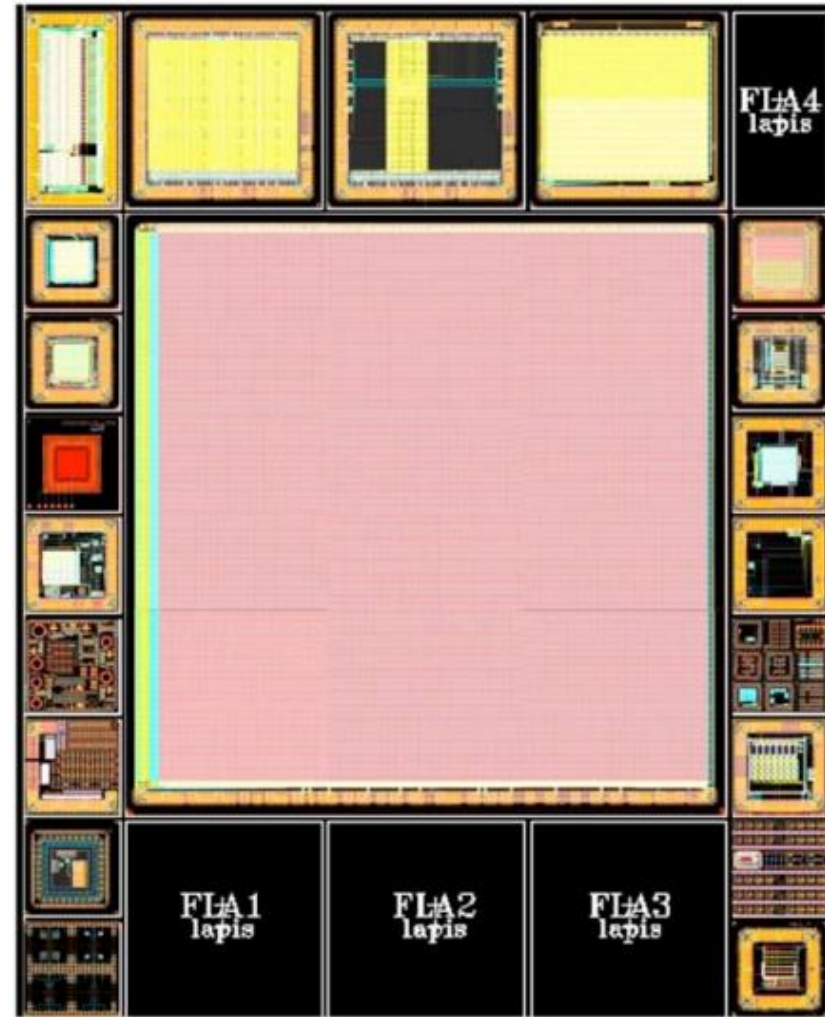
Process	0.2 μ m Low-leakage Fully-Depleted SOI CMOS 1poly+5Metal layers, MIM cap(1.5fF/mm ²), DMOS Core (I/O) voltage=1.8 (3.3)V
SOI wafer	200mmf, 720 μ mthick top Si: Cz 18 Ω cm p, 40nm thick, Buried Oxide(BOX): 200nm thick Handle wafer: Cz(n;0.7k Ω cm), FZ(n;7k), FZ(p,25k) Double SOI available
Backside process	Mechanical grind, chemical etching, Implant, Laser annealing, Al plating (thin to 50mm possible)

Multi Project Wafer(MPW)

- KEK organizes MPW runs twice a year
- Mask is shared to reduce cost of a design
- Including pixel detector chip and SOI-CMOS circuit chip
 - University & institution
KEK, FNAL, LBNL, AIST, CNS, Kyoto Univ., Tohoku Univ., Univ. Tsukuba, RIKEN-XFEL, JAXA, Krakow, Hawaii, IHEP, and more...

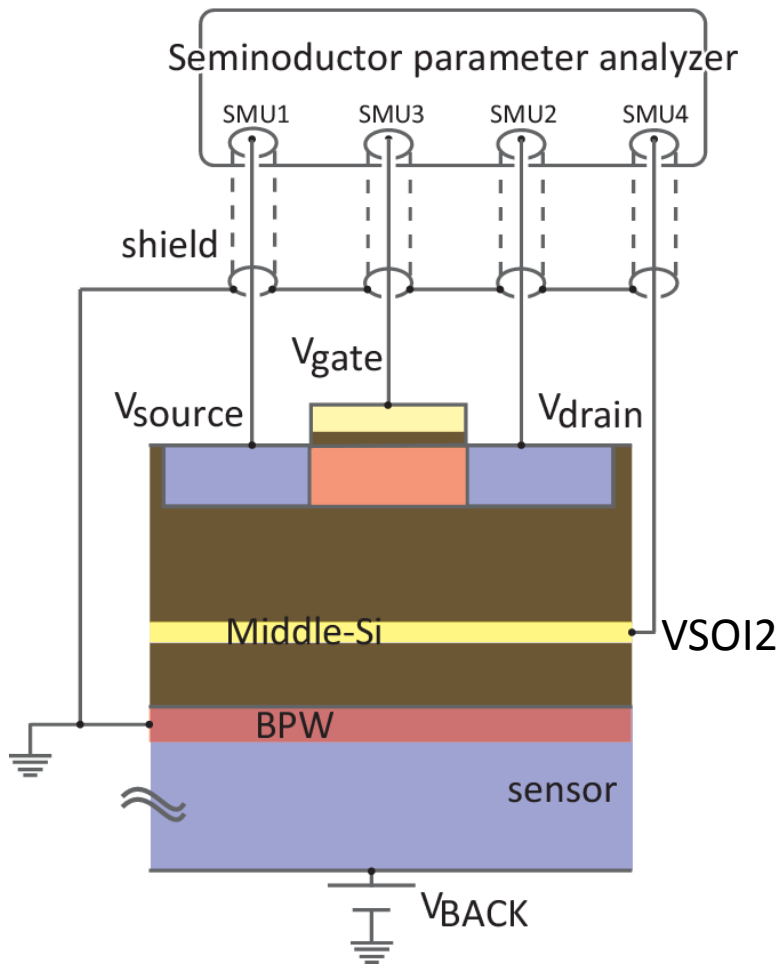


SOI-wafer

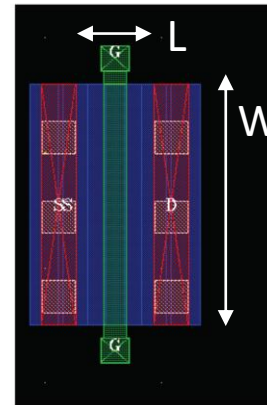


Examples of Mask layouts. : 20.6mm x 20.6mm

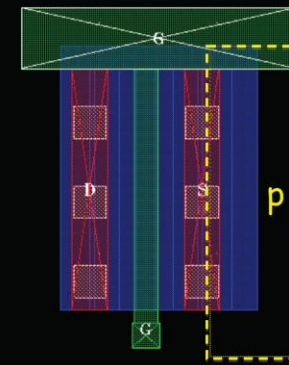
TRTEG6 body connections



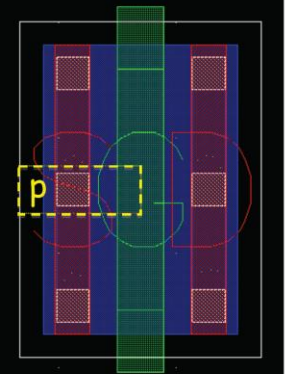
Body Floating



Source-tie



Source-tie2



NMOS

$V_{source}=0V$

$V_{drain}=1.8V$

$V_{gate}=-1.0\sim 1.7V$

$V_{BPW}=GND$

$V_{SOI2}=0V\sim -20V$

PMOS

$V_{source}=1.8V$

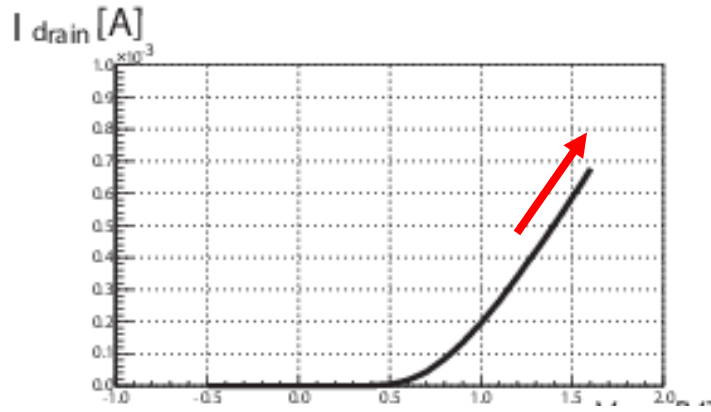
$V_{drain}=0V$

$V_{gate}=2.8\sim 0.1V$

$V_{BPW}=GND$

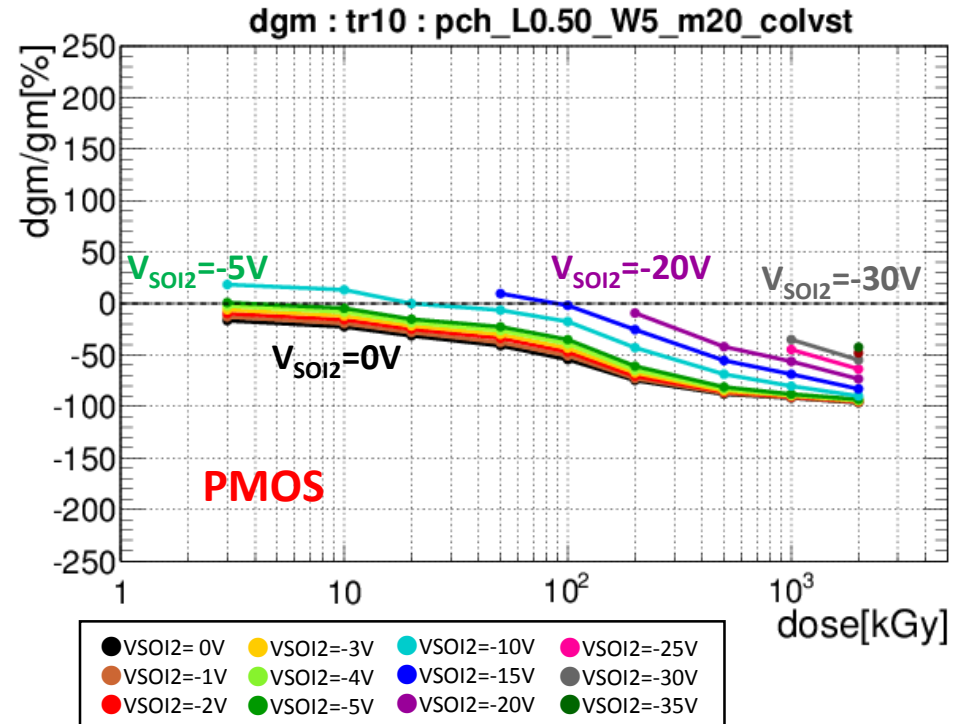
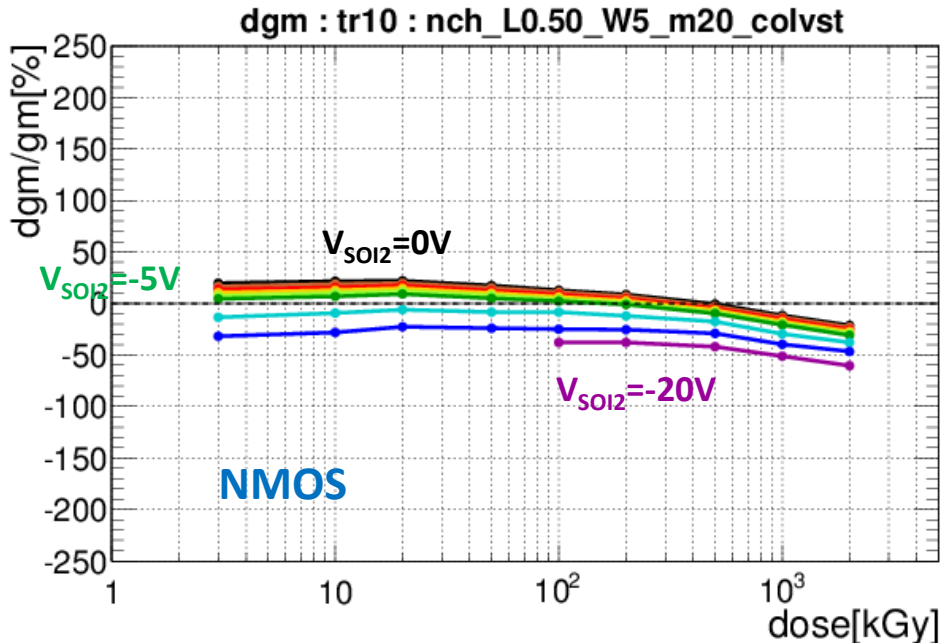
$V_{SOI2}=0V\sim -40V$

TrTEG6 gm shifts - typical TR



Trans conductance(gm)
= (I_d/V_g) @linear region

The gm shift are more complicated than vth.
The gm can be recovered to some extent.



Pixel Readout - FPGA

